

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

RECEIVED
CENTRAL FAX CENTER

JUN 08 2007

Claim Amendments

This listing of the claims will replace all prior versions,
and listings, of claims in the application:

Claim 1 (withdrawn-currently amended): A method of
fabricating filter devices, which comprises the steps of:

providing a carrier wafer carrying a plurality of filters;

providing a capping wafer;

bonding the capping wafer to the carrier wafer, with the
filters disposed in cavities between the carrier wafer and the
capping wafer; and

separating the bonded wafers into single filter devices, each
single filter device having a carrier substrate carrying at
least one filter and a capping substrate, and the at least one
filter being disposed in at least one cavity between the
carrier substrate and the capping substrate, and the at least
~~one~~ the filter devices being coupled to a wiring substrate by
at least one interconnection using flip-chip technology, the
interconnection being a solder or metal bump.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claim 2 (withdrawn): The method according to claim 1, wherein the filters are acoustic wave filters.

Claim 3 (withdrawn): The method according to claim 1, wherein the filters are Surface Acoustic Wave filters.

Claim 4 (withdrawn): The method according to claim 1, wherein the filters are Bulk Acoustic Wave filters, and each Bulk Acoustic Wave filter includes at least one Bulk Acoustic Wave resonator.

Claim 5 (withdrawn): The method according to claim 1, wherein the filters are Stacked Crystal Filters.

Claim 6 (withdrawn): The method according to claim 1, wherein the carrier substrate further includes an integrated circuit.

Claim 7 (withdrawn): The method according to claim 1, wherein the carrier substrate further includes a radio-frequency integrated circuit.

Claim 8 (withdrawn): The method according to claim 1, which further comprises performing the step of bonding the capping wafer to the carrier wafer by using a direct bonding method.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claim 9 (withdrawn): The method according to claim 1, which further comprises performing the step of bonding the capping wafer to the carrier wafer by using an anodic bonding method.

Claim 10 (withdrawn): The method according to claim 1, which further comprises performing the step of bonding the capping wafer to the carrier wafer by using an intermediate-layer bonding method.

Claim 11 (withdrawn): The method according to claim 10, which further comprises performing the intermediate-layer bonding method as an AuSi eutectic bonding method.

Claim 12 (withdrawn): The method according to claim 1, which further comprises performing a thinning step for reducing a thickness of at least one of the capping wafer and the carrier wafer, before performing the step of separating the bonded wafers into single filter devices.

Claim 13 (withdrawn): The method according to claim 12, which further comprises performing the thinning step by grinding at least one of the capping wafer and the carrier wafer.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claim 14 (withdrawn): The method according to claim 12, which further comprises performing the thinning step by etching at least one of the capping wafer and the carrier wafer.

Claim 15 (withdrawn): The method according to claim 1, which further comprises micromachining at least one of the capping wafer and the carrier wafer to provide space for the cavities.

Claim 16 (withdrawn): The method according to claim 1, which further comprises structuring the capping wafer to provide pad openings.

Claim 17 (withdrawn): The method according to claim 1, which further comprises producing interconnects before performing the step of separating the bonded wafers into single filter devices.

Claim 18 (withdrawn): The method according to claim 17, which further comprises producing the interconnects as solder or metal bumps.

Claim 19 (withdrawn): The method according to claim 1, which further comprises providing passive components on the capping wafer.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claim 20 (withdrawn): The method according to claim 1, which further comprises placing additional filters as flip-chips on top of the carrier wafer.

Claim 21 (withdrawn): The method according to claim 20, which further comprises selecting the additional filters as at least one of acoustic wave filters and active/passive ICs.

Claim 22 (currently amended): A filter device, comprising:

a carrier substrate;

at least one filter carried by said carrier substrate;

a capping substrate;

said carrier substrate and said capping substrate defining at least one cavity therebetween containing said at least one filter; and

at least one interconnection configured for coupling ~~said at least one~~ the filter device to a wiring substrate using flip-chip technology, said interconnection being a solder or metal bump.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claim 23 (original): The filter device according to claim 22,
wherein said at least one filter is an acoustic wave filter.

Claim 24 (original): The filter device according to claim 22,
wherein said at least one filter is a Surface Acoustic Wave
filter.

Claim 25 (original): The filter device according to claim 22,
wherein said at least one filter is a Bulk Acoustic Wave
filter including at least one Bulk Acoustic Wave resonator.

Claim 26 (original): The filter device according to claim 22,
wherein said at least one filter is a Stacked Crystal Filter.

Claim 27 (original): The filter device according to claim 22,
wherein said carrier substrate includes an integrated circuit.

Claim 28 (original): The filter device according to claim 27,
wherein said integrated circuit is a radio-frequency
integrated circuit.

Claim 29 (original): The filter device according to claim 22,
which further comprises at least one contact pad for coupling
said at least one filter to a wiring substrate through at
least one bonding wire.

Applic. No. 10/623,068
Amdt. dated June 7, 2007
Reply to Office action of March 21, 2007

Claims 30 and 31 (cancelled).

Claim 32 (original): The filter device according to claim 22, which further comprises passive components provided on said capping substrate.

Claim 33 (original): The filter device according to claim 22, which further comprises additional filters disposed as flip-chips on top of said carrier substrate within said at least one cavity.

Claim 34 (original): The filter device according to claim 33, wherein said additional filters are at least one of acoustic wave filters and active/passive ICs.